

Teo Cheng Kim Scholarship

In 2018, Professor Ho Teck Hua made an endowed gift of S\$250,000 to the Faculty of Engineering (now College of Design and Engineering) to support a scholarship, in memory of his late mother, Madam Teo Cheng Kim.

The bond-free scholarship of S\$7,000 per annum is awarded to deserving students for their normal course duration. This scholarship is **by invitation only**. Shortlisted students will be invited to submit the necessary documentation and may be required to attend an interview.

Selection Criteria

The applicant should:

1. Be a full-time engineering undergraduate in his/her first year of study (i.e., matriculation year).
2. Possess outstanding Singapore-Cambridge GCE A Level, local polytechnic diploma, International Baccalaureate diploma, NUS High School diploma or equivalent qualification. Participation in extra-curricular activities or community service will be considered favourably.
3. Should not be a concurrent recipient of any other form of aid such as grants, bursaries and scholarships.

Scholarship recipients need to maintain a GPA of 3.50 and above in each academic year to continue receiving the scholarship.